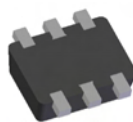


PNP DUAL SMALL SIGNAL SURFACE MOUNT TRANSISTOR
Features

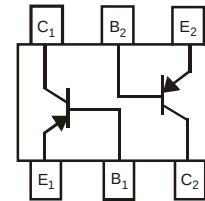
- Epitaxial Die Construction
- Complementary PNP Type Available (BC847BV)
- Ultra-Small Surface Mount Package
- **Lead Free By Design/RoHS Compliant (Note 3)**
- **"Green" Device (Notes 5 and 6)**
- **Qualified to AEC-Q101 Standards for High Reliability**



Top View



Bottom View



Device Schematic (Note 1)

Mechanical Data

- Case: SOT-563
- Case Material: Molded Plastic, "Green" Molding Compound, Note 6. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020D
- Terminal Connections: See Diagram
- Terminals: Finish - Matte Tin annealed over Alloy 42 leadframe. Solderable per MIL-STD-202, Method 208
- Marking Information: See Page 2
- Ordering Information: See Page 2
- Weight: 0.003 grams (approximate)

Maximum Ratings @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V _{CBO}	-50	V
Collector-Emitter Voltage	V _{CEO}	-45	V
Emitter-Base Voltage	V _{EBO}	-5.0	V
Collector Current	I _C	-100	mA

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 2)	P _D	150	mW
Thermal Resistance, Junction to Ambient (Note 2)	R _{θJA}	833	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

Electrical Characteristics @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Collector-Base Breakdown Voltage (Note 4)	V _{(BR)CBO}	-50	—	—	V	I _C = 10μA, I _B = 0
Collector-Emitter Breakdown Voltage (Note 4)	V _{(BR)CEO}	-45	—	—	V	I _C = 10mA, I _B = 0
Emitter-Base Breakdown Voltage (Note 4)	V _{(BR)EBO}	-5	—	—	V	I _E = 1μA, I _C = 0
DC Current Gain (Note 4)	h _{FE}	220	290	475	—	V _{CE} = -5.0V, I _C = -2.0mA
Collector-Emitter Saturation Voltage (Note 4)	V _{CE(SAT)}	—	—	-100 -400	mV	I _C = -10mA, I _B = -0.5mA I _C = -100mA, I _B = -5.0mA
Base-Emitter Saturation Voltage (Note 4)	V _{BE(SAT)}	—	-700 -900	—	mV	I _C = -10mA, I _B = -0.5mA I _C = -100mA, I _B = -5.0mA
Base-Emitter Voltage (Note 4)	V _{BE(ON)}	-600	—	-750 -820	mV	V _{CE} = -5.0V, I _C = -2.0mA V _{CE} = -5.0V, I _C = -10mA
Collector-Cutoff Current (Note 4)	I _{CBO}	—	—	-15 -4.0	nA μA	V _{CB} = -30V V _{CB} = -30V, T _A = 150°C
Gain Bandwidth Product	f _T	100	—	—	MHz	V _{CE} = -5.0V, I _C = -10mA, f = 100MHz
Output Capacitance	C _{OB}	—	—	4.5	pF	V _{CB} = -10V, f = 1.0MHz
Noise Figure	NF	—	—	10	dB	I _C = -0.2mA, V _{CE} = -5.0Vdc, R _S = 2.0KΩ, f = 1.0KHz, BW = 200Hz

- Notes:
1. Package is non-polarized. Parts may be on reel in orientation illustrated, 180° rotated, or mixed (both ways).
 2. Device mounted on FR-4 PCB, 1 inch x 0.85 inch x 0.062 inch; pad layout as shown on Diodes Inc. suggested pad layout document AP02001, which can be found on our website at <http://www.diodes.com/datasheets/ap02001.pdf>.
 3. No purposefully added lead.
 4. Short duration pulse test used to minimize self-heating effect.
 5. Diodes Inc.'s "Green" policy can be found on our website at http://www.diodes.com/products/lead_free/index.php.
 6. Product manufactured with Date Code UO (week 40, 2007) and newer are built with Green Molding Compound. Product manufactured prior to Date Code UO are built with Non-Green Molding Compound and may contain Halogens or Sb2O3 Fire Retardants.

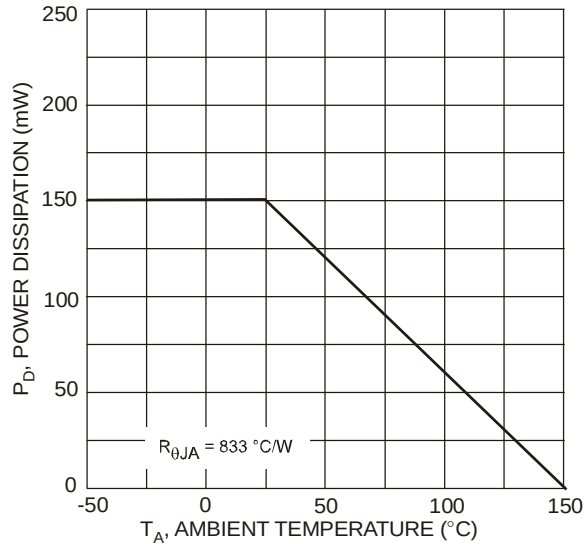


Fig. 1 Power Dissipation vs. Ambient Temperature (Note 2)

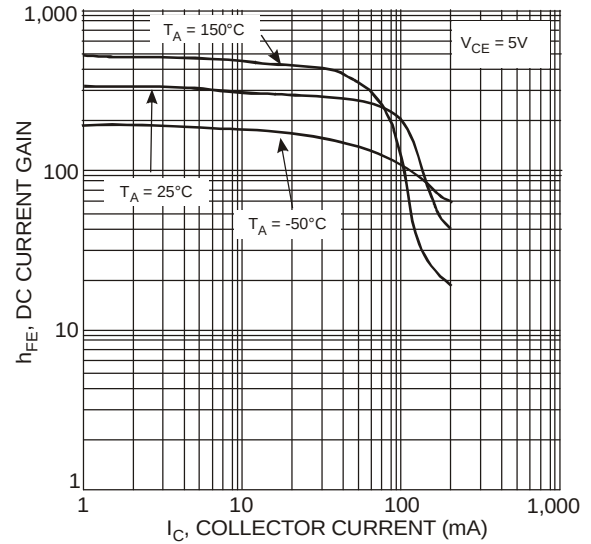


Fig. 2 Typical DC Current Gain vs. Collector Current

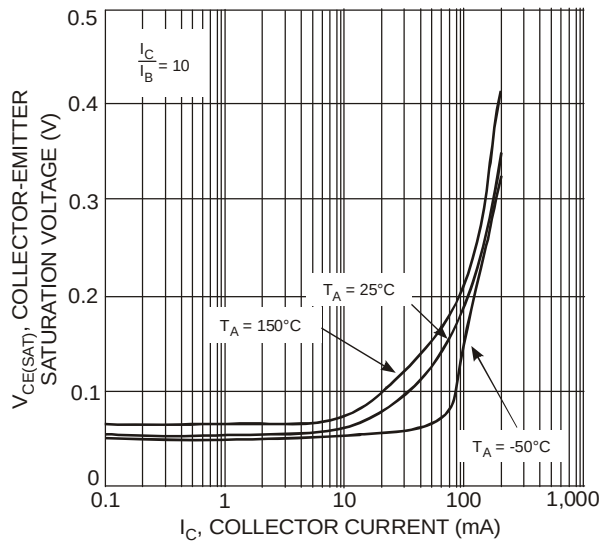


Fig. 3 Collector-Emitter Saturation Voltage vs. Collector Current

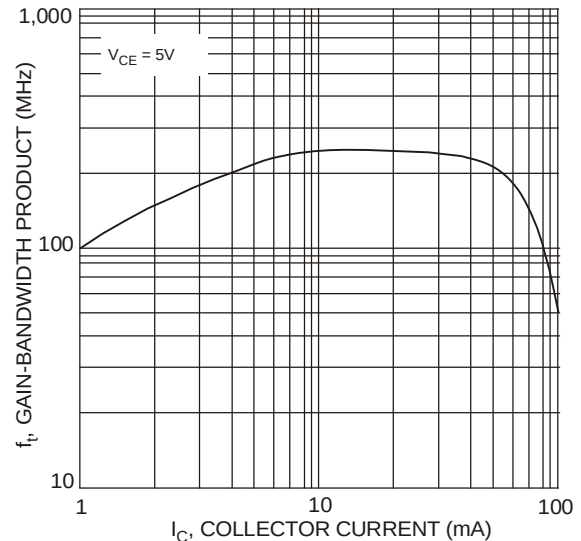


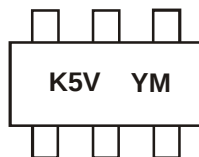
Fig. 4 Typical Gain-Bandwidth Product vs. Collector Current

Ordering Information (Note 7)

Part Number	Case	Packaging
BC857BV-7	SOT-563	3000/Tape & Reel

Notes: 7. For packaging details, go to our website at <http://www.diodes.com/datasheets/ap02007.pdf>.

Marking Information



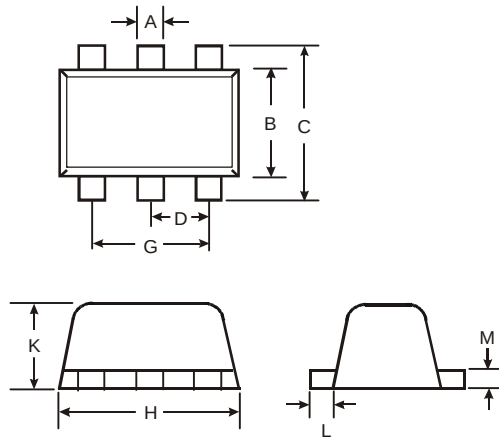
K5V = Product Type Marking Code
YM = Date Code Marking
Y = Year (ex: T = 2006)
M = Month (ex: 9 = September)

Date Code Key

Year	2003	2004	2005	2006	2007	2008	2009	2010	2011	2012	2013	2014	2015
Code	P	R	S	T	U	V	W	X	Y	Z	A	B	C

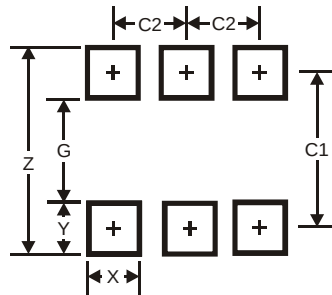
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D

Package Outline Dimensions



SOT-563			
Dim	Min	Max	Typ
A	0.15	0.30	0.20
B	1.10	1.25	1.20
C	1.55	1.70	1.60
D	-	-	0.50
G	0.90	1.10	1.00
H	1.50	1.70	1.60
K	0.55	0.60	0.60
L	0.10	0.30	0.20
M	0.10	0.18	0.11
All Dimensions in mm			

Suggested Pad Layout



Dimensions	Value (in mm)
Z	2.2
G	1.2
X	0.375
Y	0.5
C1	1.7
C2	0.5

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